

STANDARDS NEWSLETTER

(INDIA REGION)

Volume 5

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Deliver on Consistency, Reliability and Quality

MESSAGE



David Bergman
VP - Standards & Technology

Standards Development activities in India region are maturing. I can see a significant interest from Indian industries related to Electronic Manufacturing, Wire Harness, EV, Aerospace and Defence and PCB fabrication. Recently, we have witnessed the engagement at the project review meetings led by industry leaders at IPC flagship event 'IEMI' (Integrated Electronics Manufacturing & Interconnections) at Bengaluru on 29th July 2024.

We have noticed enthusiastic response on recently published Automotive Supplier Checklist (IPC 1771) which has developed by Indian Automotive organisations. The efforts are underway on Consumer Electronics sector challenges and also with DGQA in review committee of their JSS standards and relevant training support. In coming time, we will be focussing to have more OEMs involvement in Standard Development committees.

IPC invites the industry to come forward and join the Standard Development activities to help 'Build Electronics Better'.

EVENTS @ STANDARDS DEVELOPMENT

Forthcoming Standards Development committee meeting/ event:

STANDARDS DEVELOPMENT COMMITTEE MEETINGS
October 5-10, 2024
McKimmon Center | Raleigh, NC

29- 30
January 2025
VIENNA- AUSTRIA
**Pan-European
Electronics Design
Conference**

MARCH 15-20
MEETINGS + COURSES
MARCH 18-20
CONFERENCE + EXHIBITION
ANAHEIM CONVENTION CENTER, CA

**REIMAGINE
THE POSSIBILITIES**

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STANDARDS DEVELOPMENT MEETINGS @ IEMI

100+ members from Government and Electronics industry attended IPC Standard Development meetings at Bengaluru on July 29. These attendees were from EMS, Wire Harness, PCB Design, EV and Consumer Electronics domain shared the progress of each group with VP Standards (Mr. David Bergman) and ED (Mr. Gaurab Majumdar).








During these physical interaction with industry experts, there are lot of new interest from more industry experts to join IPC Standard Development committees and work towards industry standards development.

Details of Std Dev. Meetings held:

1. IPC-A-610 (7-31B-IND), IPC/WHMA-A-620 (7-31F-IND), IPC-A-630 (7-31 J IND)
2. Challenges in Consumer Electronics sector organisations
3. Update on PCB Test Lab
4. IPC 9911, IPC 2232



Meet India Committee Chair:

				
IPC-A-610 (7-31B-IND)	IPC/WHMA-A-620 (7-31F-IND)	IPC-A-630 (7-31 J IND)	IPC 2232 (Guideline for Printed Board Design and Manufacturing of IOT Products)	IPC 9911 Guideline for Automotive Electronics Printed Board Thermal Management & Electronic Component Derating)
Siraj Puthanpurayil Schneider Electric IT Business India Pvt. Ltd.	Gp. Capt. Sudarshan Jagirdar Russell Techsys	Prakash Rukmaiah Ray-Q Interconnection Technologies India Pvt. Ltd.	Savita.R.Ganjigatti SIENNA ECAD Technologies Pvt. Ltd.	Anand Kumar SN Polisetty Niqo Robotics

SUPPORT ON JSS 52302: 2024

IPC join hands with DGQA (Directorate General of Quality Assurance) for the updation of their JSS (Joint Service Specification), Training support and also possible support for establishing the PCB Test Lab at India.

Against this drive, IPC experts participated in the review activity of exiting version of JSS 52302 (Specification for Printed Circuit Boards, Rigid, Multilayer, Through Hole).



IPC organised a technical awareness session on 6th June 2024 to DGQA officials (12 nos.) at HI-Q Electronics Pvt. Ltd., Hosur.

During this session, IPC experts given an awareness on IPC-A-600, IPC 6012 and also on PCB Test Lab equipment and Test processes.



UPDATE: IPC 1771 – AUTOMOTIVE SUPPLIER CHECKLIST

The first ever Standard document released from India, IPC 1771 (Automotive Supplier Checklist) has now been uploaded on IPC webpage. This checklist is now available free of cost via following URL: www.go.ipc.org/1771checklist



This download data of this checklist (466 nos. from 61 countries) in short time proves the utility and importance of this document.



IMPROVING QUALITY PROCESSES FOR CONSUMER ELECTRONICS DEVICE MANUFACTURING

IPC has teamed up with ICEA (India Cellular and Electronics Association) to study, find & improvise “Standards” applicable for design & manufacturing process in the assembly of printed circuit boards used in building consumer electronics devices, gadgets & appliances.



Against this initiative, experts from Consumer Electronics organisation has been constituted under the chairmanship of Mr. Ashish J Micheal from Jio Platform Ltd. and started working on having challenges faced in the manufacturing of consumer electronics products.

A physical/ virtual workshop has also been arranged by IPC on 22nd June 2024 at IPC Delhi premises and expected to come out with a curriculum for consumer electronics organisations.

MEMBER ENGAGEMENT: MEETING WITH STANDARDS DEVELOPMENT MEMBERS

Standard Development activities in India region is in its peak in terms of number of task teams, projects and members involvement in short span of time.

Behind this, ongoing efforts on having the continuous meetings with members at various parts of India physically and virtually to keep involved with members and finding out next actions in standard development.

Few productive meetings held in last few weeks were Syrma SGS Technology Ltd. , Schneider Electric IT Business India Pvt. Ltd., Amphenol FCI, Rossell Techsys, Sasmos HET Technologies Ltd., Centum Electronics Ltd. etc....



CALL FOR PARTICIPATION

The 7-31j Task Group is currently working on IPC-A-630A providing the requirements for the manufacture, inspection and test for electronic box assemblies. We welcome anyone interested in this topic to join the task group.

The A-Team is currently working to make recommendations on the technical comments provided during the Final Draft for Industry Review period, and a task group meeting will be held later this summer.

The 5-21Q task group invites volunteers to participate in the development of the IPC-7077 Requirements and Acceptance of Wire Bonding in the Microelectronic Assembly. The IPC-7077 is currently in the working draft stage and the task group desires new input from those with relevant expertise.

To join this task group visit www.ipc.org/join-committee-home-page

New Document: IPC-2201, Base Material Selection Guide for Printed Boards -- Call for Participation

The 1-10D Task Group has been created to work on a new document, IPC-2201, Base Material Selection Guide for Printed Boards. The objective is to develop pertinent information for each application area for board designers to use in their decision making process based on IPC-4101 and IPC-4103. We welcome anyone interested in this topic to join the task group by filling out the "Join a Committee" form at www.ipc.org/join-committee-home-page.

The PEDC team invites engineers, researchers, academics, technical experts, and industry leaders to submit abstracts for the Pan-European Electronics Design Conference.

Topics to be covered are Silicon-to-Systems, Design for Excellence, Design Software and Tools, Design Process and Product Life Cycle.

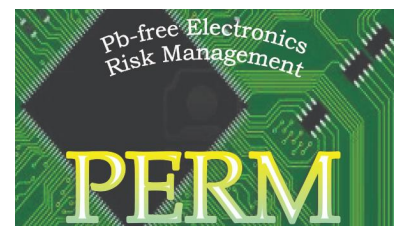
Visit <https://pedc.eu/> for more information

Pb-Free Electronics Risk Management (PERM) Council

There is no electronics market sector currently immune from Pb-free. Ask yourself the following questions:

1. Is your company already dealing with Pb-free electronics?
2. Are Pb-free electronics required by your customers?
3. Do you build products for any of the following harsh environments?
 - Aerospace • Medical • Military • Automotive
4. Do your products require a long service life?

Visit www.ipc.org/solutions/pb-free-electronics-risk-management-perm-council



STANDARDS: CURRENT STATUS
Final Draft for Industry Review

IPC-1753 WAM2	Laboratory Report Standard
IPC-4203C	Cover and Bonding Material for Flexible Printed Circuitry
IPC-4204C	Flexible Metal-Clad Dielectrics for Use in Fabrication of Flexible Printed Boards
IPC-6011A	Generic Performance Specification for Printed Boards
IPC-7527A	Requirements for Solder Paste Application
IPC-8981	Quality and Reliability of E-Textiles Wearables
IPC-9716	Requirements for Automated Optical Inspection (AOI) Process Control for Printed Board Assemblies
IPC-A-630A	Acceptability Standard for Manufacture, Inspection, and Testing of Electronic Enclosures
IPC-HDBK-005A	Guide to Solder Paste Assessment
IPC-J-STD-002F	Solderability Tests for Component Leads, Terminations, Lugs, Terminals and Wires

Project Approved

IPC-2201	Requirements for Physics of Failure Analysis for Components and Assemblies
IPC-2611A	Generic Requirements for Electronic Product Documentation
IPC-2612-1A	Sectional Requirements for Electronic Diagramming Symbol Generation Methodology
IPC-2612A	Sectional Requirements for Electronic Diagramming Documentation (Schematic and Logic Descriptions)
IPC-4557	Specification for Electrolytically Deposited Nickel/Gold Surface Finish for Printed Board Applications
IPC-6911	Acceptability of Additively Manufactured Electronics (AME)
IPC-7070	Guidelines for Printed Board Component Mounting
IPC-7077	Requirements and Acceptance of Wire Bonding in the Microelectronic Assembly
IPC-9205	Evaluating Electrochemical Performance of Electronics Manufacturing Materials and Processes
IPC-HDBK-001A	Handbook and Guide to Supplement J-STD-001G and J-STD-001G - Revision A
IPC/JEDEC J-STD-033E	Handling, Packing, Shipping and Use of Moisture, Reflow, and Process Sensitive Devices
IPC/JEDEC J-STD-609C	Marking, Symbols, and Labels of Leaded and Lead-Free Terminal Finished Materials Used in Electronic Assembly



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